





ZLLS350

40V LOW LEAKAGE SCHOTTKY DIODE

Features

- Low V_F
- 380mA continuous current rating
- Low profile SOD523 package
- Lead Free By Design/RoHS Compliant (Note 1)
- "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

Description

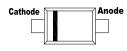
Packaged in the SOD523 package offering an ideal low V_F/I_R performance combined with a low package height making the device suitable for various converter, charger and LED driver circuits

Mechanical Data

- Case: SOD523
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.001 grams (approximate)







Top View Pin-Out

Ordering Information (Note 3)

| B (N) | | 5 |
|-------------|---------|------------------|
| Part Number | Case | Packaging |
| ZLLS350TA | SOD-523 | 3000/Tape & Reel |

Notes:

- 1. No purposefully added lead.
- 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
- 3. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



L3 = Product Type Marking Code



ZLLS350

Maximum Ratings @T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

| Characteristic | Symbol | Value | Unit |
|--|------------------|-------------|------|
| DC Blocking Voltage | V_{RM} | 40 | V |
| Continuous Forward current | I _F | 380 | mA |
| Average Peak Forward Current; duty cycle = 50% | I _{FAV} | 650 | mA |
| Non-Repetitive Forward Current @ t < 100µs @ t < 100ms | I _{FSM} | 6.0 1.3 | А |
| Power Dissipation at T _A = 25°C (Note 4) | P _D | 357 | mW |
| Power Dissipation at T _A = 25°C (Note 5) | P _D | 413 | mW |
| Operating and storage temperature range | T _{STG} | -55 to +150 | °C |
| Junction Temperature | TJ | 150 | °C |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit |
|---|----------------|-------|------|
| Thermal Resistance Junction to Ambient (Note 4) | $R_{	heta JA}$ | 350 | °C/M |
| Thermal Resistance Junction to Ambient (Note 5) | $R_{	heta JA}$ | 303 | °C/W |

Electrical Characteristics @TA = 25°C unless otherwise specified

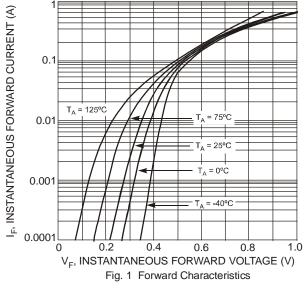
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
|-------------------------------|-----------------|-----|------|------|------|---------------------------------------|-------------------------|
| Reverse Breakdown Voltage | $V_{(BR)R}$ | 40 | 53 | - | V | $I_R = 100 \mu A$ | |
| Forward Voltage Drop (Note 6) | | - | 395 | 450 | | $I_F = 30mA$ | |
| | | - | 430 | 520 | V | $I_F = 50 \text{mA}$ | |
| | V _F | - | 490 | 635 | | $I_F = 100 \text{mA}$ | |
| | | - | 650 | 1000 | | $I_F = 275 \text{mA}$ | |
| Leakage Current | I _R | - | 0.15 | 4 | μΑ | $V_R = 30V$ | |
| Total Capacitance | C _T | | 2.5 | 6 | | f = 1MHz; V _R = 30V | |
| Reverse Recovery Time | | | | | | Switch from I _F = 100mA to | |
| | t _{rr} | | | 1 | | nS | $I_R = 100 \text{mA}$. |
| | | | | | | Measured at I _R = 10mA | |

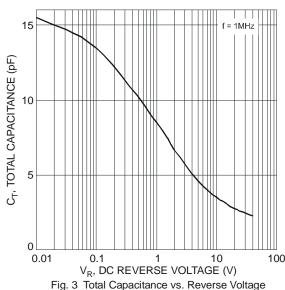
Notes:

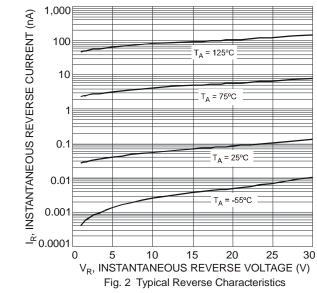
- 4. For a single device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of 1oz copper in still air conditions
- 5. As above measured at t < 5 seconds
- 6. Measured under pulsed conditions. Pulse width ≤ 300µs; duty cycle ≤ 2%



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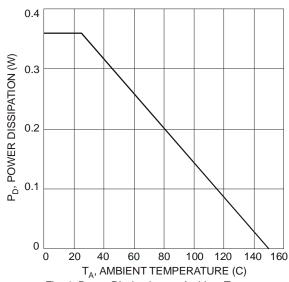
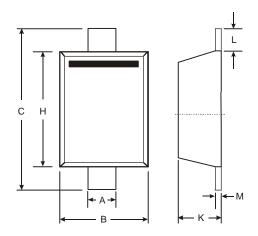


Fig. 4 Power Dissipation vs. Ambient Temperature

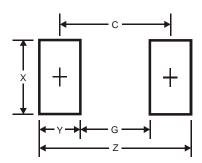
Package Outline Dimensions



| SOD-523 | | | |
|----------------------|------|------|--|
| Dim | Min | Max | |
| Α | 0.25 | 0.35 | |
| В | 0.70 | 0.90 | |
| С | 1.50 | 1.70 | |
| Н | 1.10 | 1.30 | |
| K | 0.55 | 0.65 | |
| L | 0.10 | 0.30 | |
| M | 0.10 | 0.12 | |
| All Dimensions in mm | | | |



Suggested Pad Layout



| Dimensions | Value (in mm) |
|------------|---------------|
| Z | 2.3 |
| G | 1.1 |
| Х | 0.8 |
| Y | 0.6 |
| С | 1.7 |

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